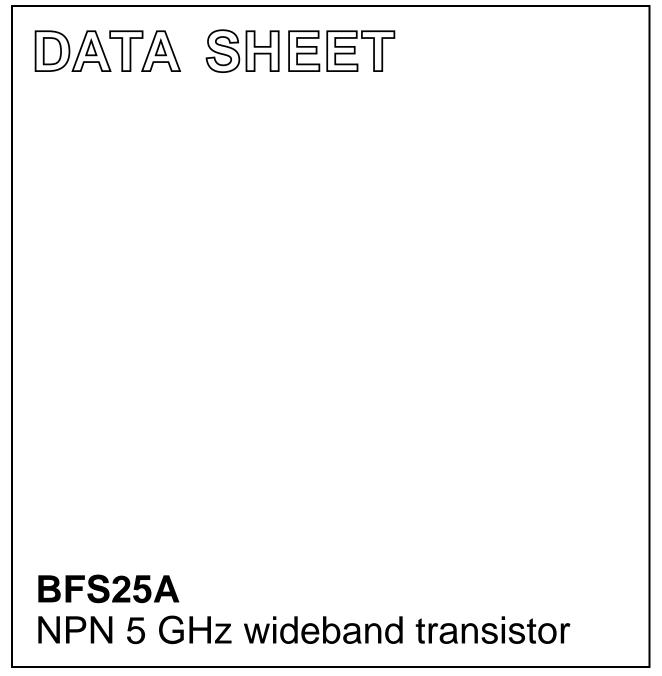
DISCRETE SEMICONDUCTORS



Product specification

December 1997



PINNING

PIN

1

2

3

FEATURES

- Low current consumption
- Low noise figure
- Gold metallization ensures
 excellent reliability
- SOT323 envelope.

DESCRIPTION

NPN transistor in a plastic SOT323 envelope.

It is designed for use in RF amplifiers and oscillators in pagers and pocket phones with signal frequencies up to 2 GHz.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	—	-	8	V
V _{CEO}	collector-emitter voltage	open base	_	_	5	V
I _C	DC collector current		-	-	6.5	mA
P _{tot}	total power dissipation	up to $T_s = 170 \text{ °C}$; note 1	_	_	32	mW
h _{FE}	DC current gain	$I_{C} = 0.5 \text{ mA}; V_{CE} = 1 \text{ V}; T_{j} = 25 \text{ °C}$	50	80	200	
f _T	transition frequency	$I_{C} = 1 \text{ mA}; V_{CE} = 1 \text{ V}; f = 1 \text{ GHz};$ $T_{amb} = 25 \text{ °C}$	3.5	5	-	GHz
G _{UM}	maximum unilateral power gain	$I_c = 0.5 \text{ mA}; V_{CE} = 1 \text{ V}; f = 1 \text{ GHz};$ $T_{amb} = 25 \text{ °C}$	-	13	_	dB
F	noise figure	$I_c = 0.5 \text{ mA}; V_{CE} = 1 \text{ V}; \text{ f} = 1 \text{ GHz};$ $T_{amb} = 25 \text{ °C}$	-	1.8	-	dB

DESCRIPTION

Code: N6

base

emitter

collector

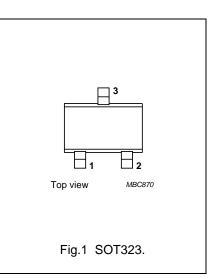
LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	8	V
V _{CEO}	collector-emitter voltage	open base	-	5	V
V _{EBO}	emitter-base voltage	open collector	-	2	V
I _C	DC collector current		-	6.5	mA
P _{tot}	total power dissipation	up to $T_s = 170 \ ^{\circ}C$; note 1	-	32	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	175	°C

Note

1. T_s is the temperature at the soldering point of the collector tab.



THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	THERMAL RESISTANCE
R _{th j-s}	thermal resistance from junction to soldering point	up to T _s = 170 °C; note 1	190 K/W

Note

1. T_s is the temperature at the soldering point of the collector tab.

CHARACTERISTICS

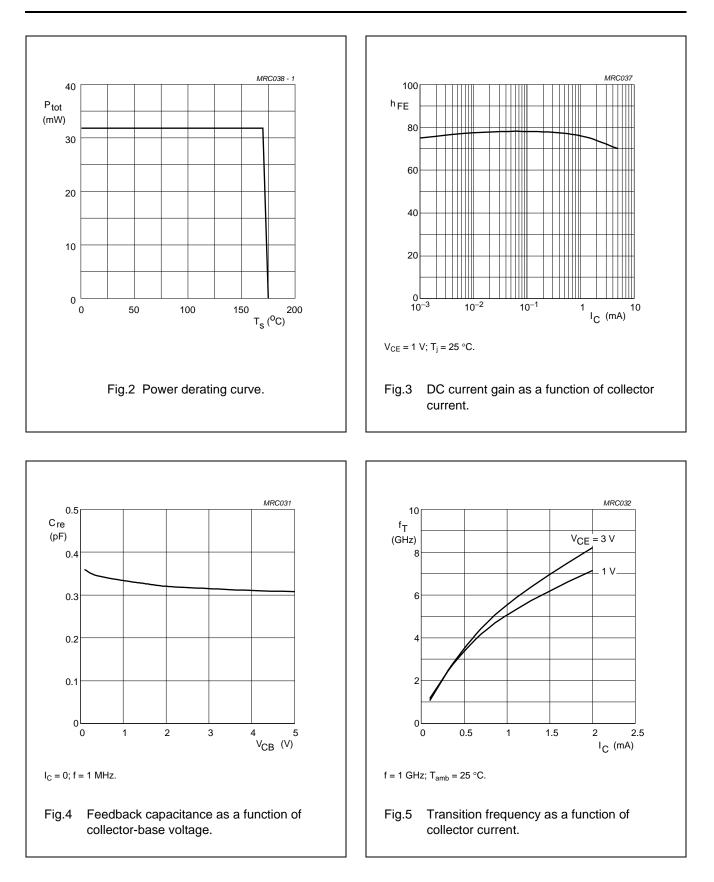
 $T_j = 25 \ ^{\circ}C$, unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = 5 V	-	-	50	nA
h _{FE}	DC current gain	I _C = 0.5 mA; V _{CE} = 1 V	50	80	200	
C _{re}	feedback capacitance	I _C = 0; V _{CB} = 1 V; f = 1 MHz	-	0.3	0.45	pF
f _T	transition frequency	$I_{C} = 1 \text{ mA}; V_{CE} = 1 \text{ V}; f = 1 \text{ GHz};$ $T_{amb} = 25 ^{\circ}\text{C}$	3.5	5	-	GHz
G _{UM}	maximum unilateral power gain (note 1)	I_{C} = 0.5 mA; V_{CE} = 1 V; f = 1 GHz; T _{amb} = 25 °C	-	13	-	dB
F	noise figure	$\Gamma_{s} = \Gamma_{opt}$; I _C = 0.5 mA; V _{CE} = 1 V; f = 1 GHz; T _{amb} = 25 °C	-	1.8	-	dB
		$\Gamma_{s} = \Gamma_{opt}$; I _C = 1 mA; V _{CE} = 1 V; f = 1 GHz; T _{amb} = 25 °C	_	2	_	dB

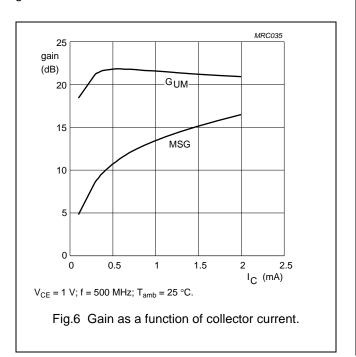
Note

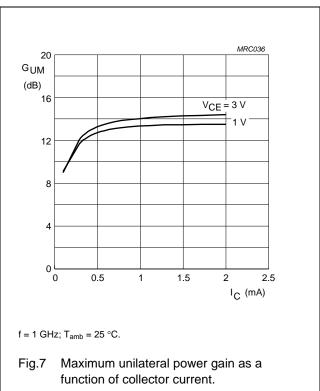
1. G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero and

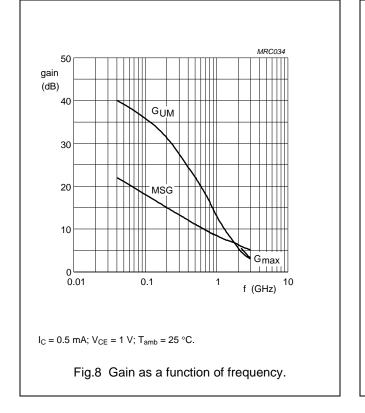
$$G_{UM} = 10 \log \frac{|S_{21}|^2}{(1 - |S_{11}|^2)(1 - |S_{22}|^2)} dB.$$

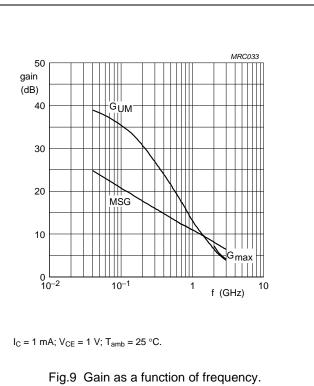


In Figs 7 to 9, G_{UM} = maximum unilateral power gain; MSG = maximum stable gain; G_{max} = maximum available gain.









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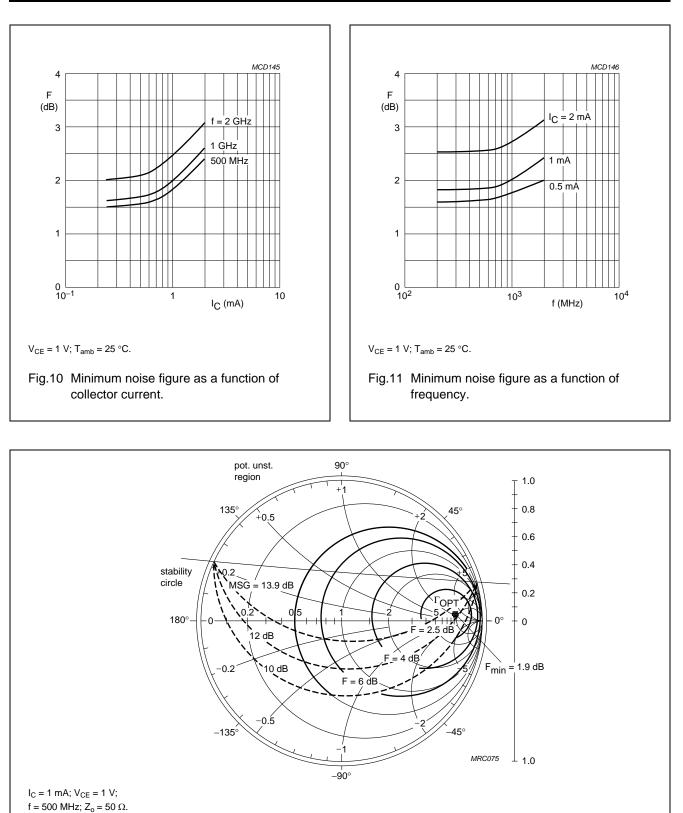
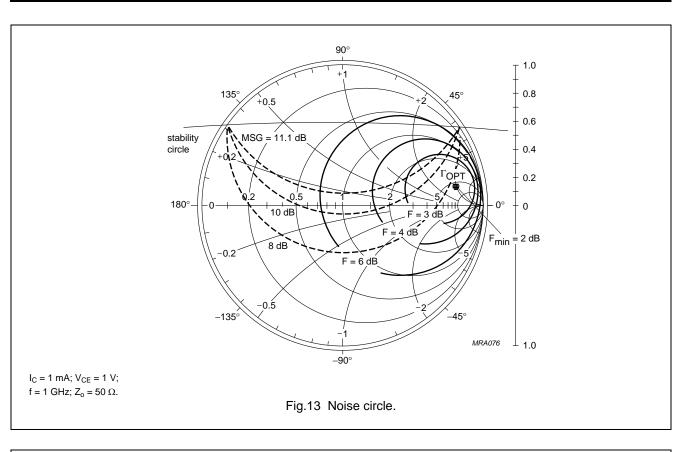
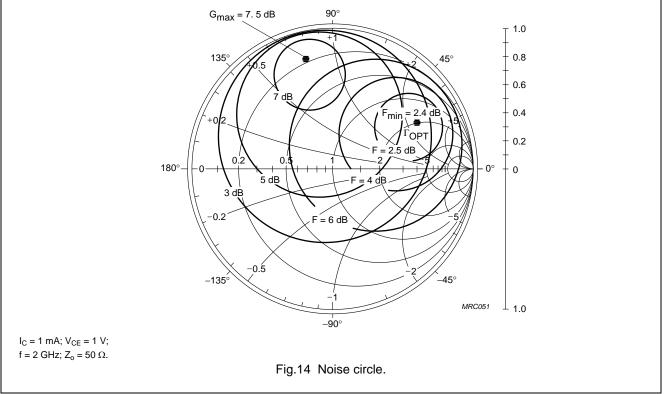
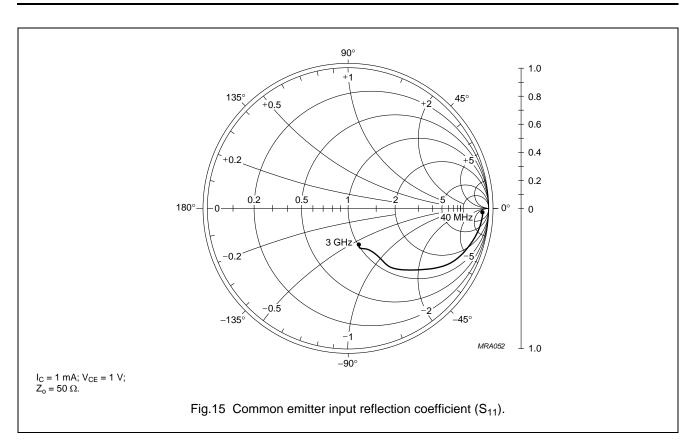
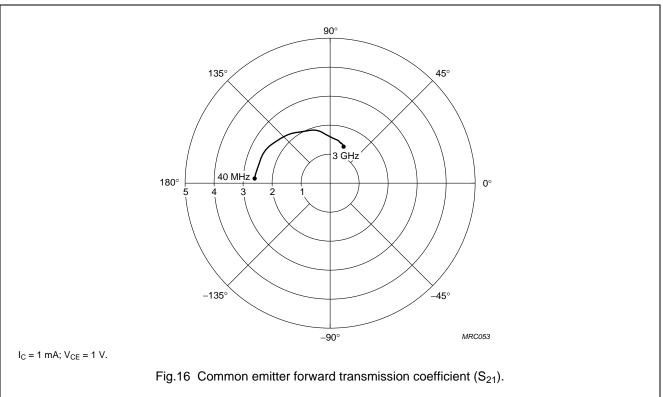


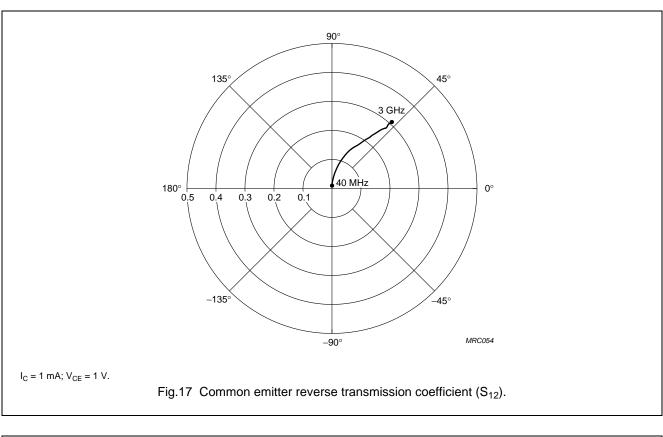
Fig.12 Noise circle.

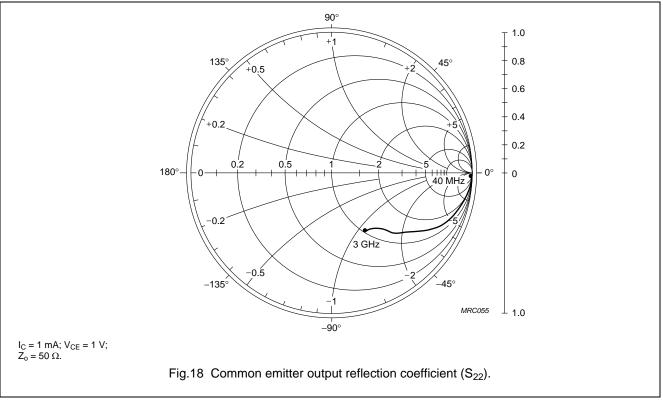




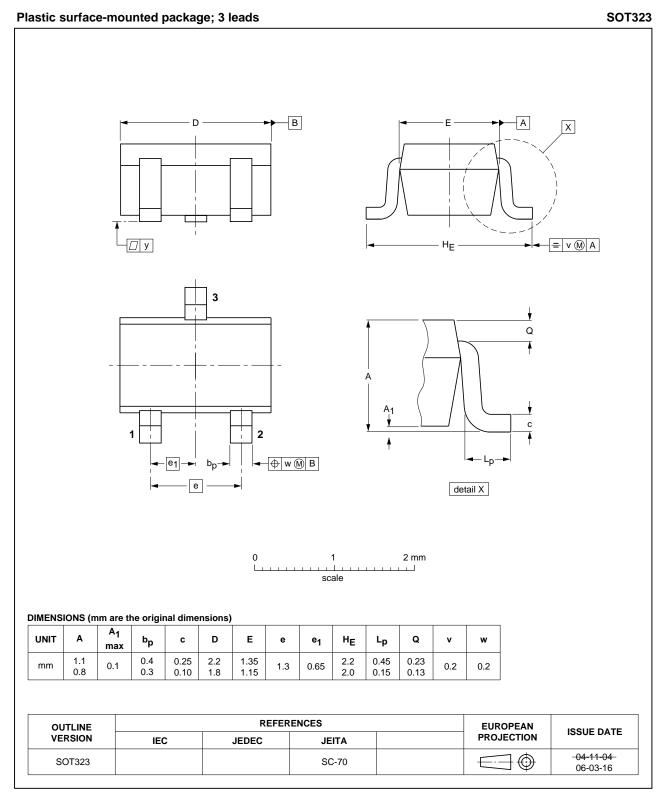








PACKAGE OUTLINE



BFS25A

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Contact information

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